

Applic. No.: 09/436,598

Marked-Up Version of the Amended Claims:

Claim 1 (twice amended). A power semiconductor module, comprising:

semiconductor components and connecting elements;

a plastic housing having an interior, a flat inside, and [connecting element] openings formed therein, said openings having an inner side adjacent said interior;

a substrate disposed in said plastic housing defining a housing base of said plastic housing, said substrate containing a ceramic plate having a top side and a bottom side with a top metallization layer disposed on said top side and a bottom metallization layer disposed on said bottom side, said top metallization layer facing said interior of said plastic housing being patterned in order to form conductive interconnects and equipped for and receiving said semiconductor components and said connecting elements;

terminal elements in said plastic housing for providing external terminals, said terminal elements having lugs, said terminal elements in the region of said lugs being press-fitted into said [connecting element] openings in said plastic housing, said terminal elements bearing on said flat inside of

said plastic housing, and said lugs pressing against said inner side of said openings for fixing said terminal elements in position; and

wires bonded to said terminal elements and to said semiconductor components.